Special Issue

Recent Advances in Millimeter-Wave Components and Integrated Technologies

Message from the Guest Editors

With the rapid development of fields such as 5G communication, millimeter-wave radar, satellite communication, smart cars, and intelligent Internet of Things, low-cost, high-performance, and miniaturized millimeter-wave devices and integrated systems are playing a crucial role in these fields. The aim of this Special Issue of *Electronics* is to present state-of-the-art investigations in millimeter-wave components, chips, and integrated technologies for current and future applications. We invite researchers to contribute original and unique articles, as well as sophisticated review articles. Topics of interest for this Special Issue include, but are not limited to, the following areas:

- Reconfigurable millimeter-wave components;
- Reconfigurable millimeter-wave antenna;
- New millimeter-wave integrated passive device (IPD);
- New millimeter-wave substrate integrated waveguide (SIW) components:
- Advanced TSV/TGV packaging and integration technology:
- Millimeter-wave packaged antenna (AiP) technology;
- GaN, GaAs, and silicon-based millimeter-wave chips.

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Deadline for manuscript submissions

closed (15 May 2024)



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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.8 days after submission; acceptance to publication is undertaken in 2.4 days (median values for papers published in this journal in the first half of 2025).

